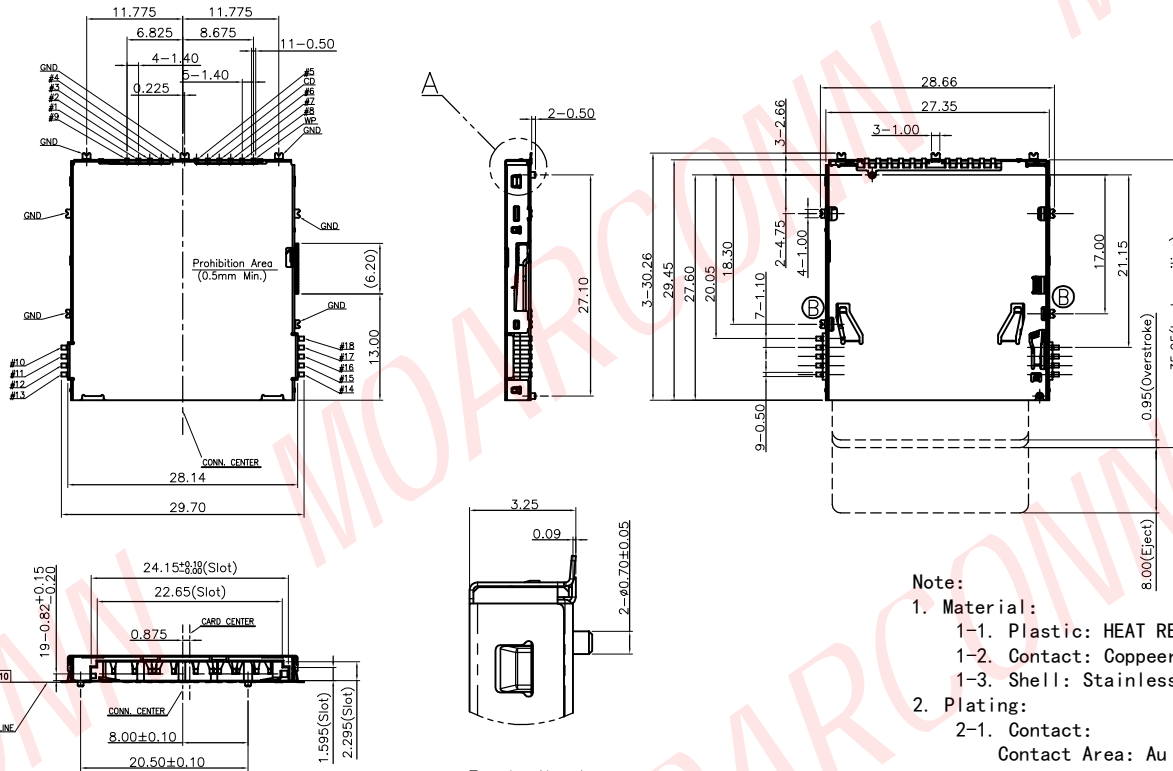
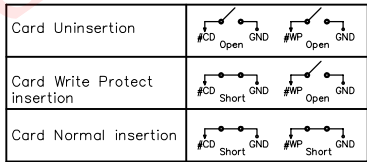


All materials, plating and process meet HF requirements.



Detail A
Scale 4 : 1

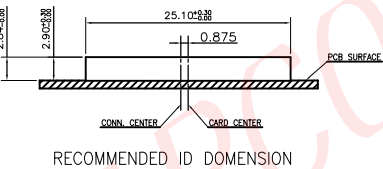
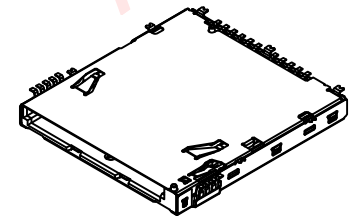


Pin Assignment

Pin #	SD Mode	UHS II Mode	SD Express Card	Pin #	SD Mode	UHS II Mode	SD Express Card
#1	CD/DAT3		PERST#	#11	D0+	PCIe_Tx+	
#2	CMD			#12	D0-	PCIe_Tx-	
#3	VSS1	VSS1	VSS1	#13	VSS4	VSS4	
#4	VDD	VDD1	VDD1	#14	VDD2	VDD2	
#5	CLK			#15	D1-	PCIe_Rx-	
#6	VSS2	VSS2	VSS2	#16	D1+	PCIe_Rx+	
#7	DAT0	RCLK+	REFCLK+	#17	VSS5	VSS5	
#8	DAT1	RCLK-	REFCLK-	#18		VDD3	
#9	DAT2	CLKREQ#	CD			Card Detect	
#10		VSS3	VSS3	WP		Write Protect	

Note:

- Material:
 - Plastic: HEAT RESISTANCE LCP, Black, HF, UL94V-0, RECOMMENDED PCB LAYOUT (TOP VIEW) TOLERANCE UNLESS OTHERWISE SPEC ±0.05
 - Contact: Copper Alloy
 - Shell: Stainless Steel
- Plating:
 - Contact:
 - Contact Area: Au 1μ" min. Plating Over Ni 50μ" min.
 - Soldertile: Gold Flash Plating Over Ni 50μ" min.
 - Shell:
 - Solderable Ni 50μ" min. Over All
- Contact And Soldertile Coplanarity to be 0.10mm max.
- Electrical Characteristics:
 - Contact Current Rating: 0.5Amperes.
 - Dielectric Withstanding Voltage: AC500V r.m.s.
 - Insulation Resistance: 1000 Megohms
 - Contact Resistance: 100 Miliohms Maximum.
- Environmental:
 - Operating Temperature: -25° C to +85° C.
 - Salty spray: 48H
- Steel mesh: Recommending a metal mask more than 0.13mm thick.
If use a metal mask less than 0.13mm thick, please confirm solderability.



MOARCONN MORE CONNECTIONS SMART FUTURE		DONG GUAN MOARCONN ELECTRONIC Co., Ltd.			
DIMENSIONS INIT: mm UNLESS OTHERWISE SPECIFIABLE		PRODUCT NAME : SD7.0 Bottom H3.25 Push-Push		DRAWING: Aaron DATE: 2024.04.18	
DIMENSION TOLERANCE		PRODUCT NO. : SD325-T1150-01		CHECK: DATE:	
X.X: ± 0.35 X.XX: ± 0.20 X.XXX: ± 0.10 ANGULAR: ± 2'		DRAWING NO. : D-SD325-T1150-01		APPROVED: DATE:	
		SCALE: 1:1		DWG ID: C D REV.: B PAGE: 1 OF 1	

REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
B	----	Modify the shell to add holes	Aaron	2024.04.18
A	----	INITIAL EDITION	Brook	2023.05.10